

ESA8UN324(2/4)(A)-(60/70)(J/T)(G/S)-S

32MByte (8M x 32) CMOS EDO DRAM Module

General Description

The ESA8UN324(2/4)(A)-(60/70)(J/T)(G/S)-S is a high performance, EDO (Extended Data Out) 32-megabyte dynamic RAM module organized as 4M words by 32bits, in a 72-pin, leadless, single-in-line memory module (SIMM) package. ESA8UN3242(A) supports 2K refresh. ESA8UN3244(A) supports 4K refresh.

The module utilizes sixteen, Fujitsu MB811(7/6)405A-(60/70)PJ CMOS 4Mx4 EDO dynamic RAM in a surface mount package on an epoxy laminate substrate. Each device is accompanied by a decoupling capacitor for improved noise immunity.

Control lines provided are such that byte control is possible.

Features

- High Density: 32MByte
- Fast Access Time of 60/70 ns (max.)
- Low Power:
 - Active (60/70 ns)
 - 4.7/4.0 W (max.) - 2K
 - 3.4/2.9 W (max.) - 4K
 - 176mW (max.) - Standby (TTL)
 - 88mW (max.) - Standby (CMOS)
- TTL-compatible inputs and outputs
- Separate power and ground planes
- Single power supply of 5V±10%
- Height: 1.00 inch
- Devices: PCB accepts only 400mil QCAS device (ESA8UN3242)
 PCB accepts 300 and 400mil QCAS device (ESA8UN3242A)

ABSOLUTE MAXIMUM RATINGS

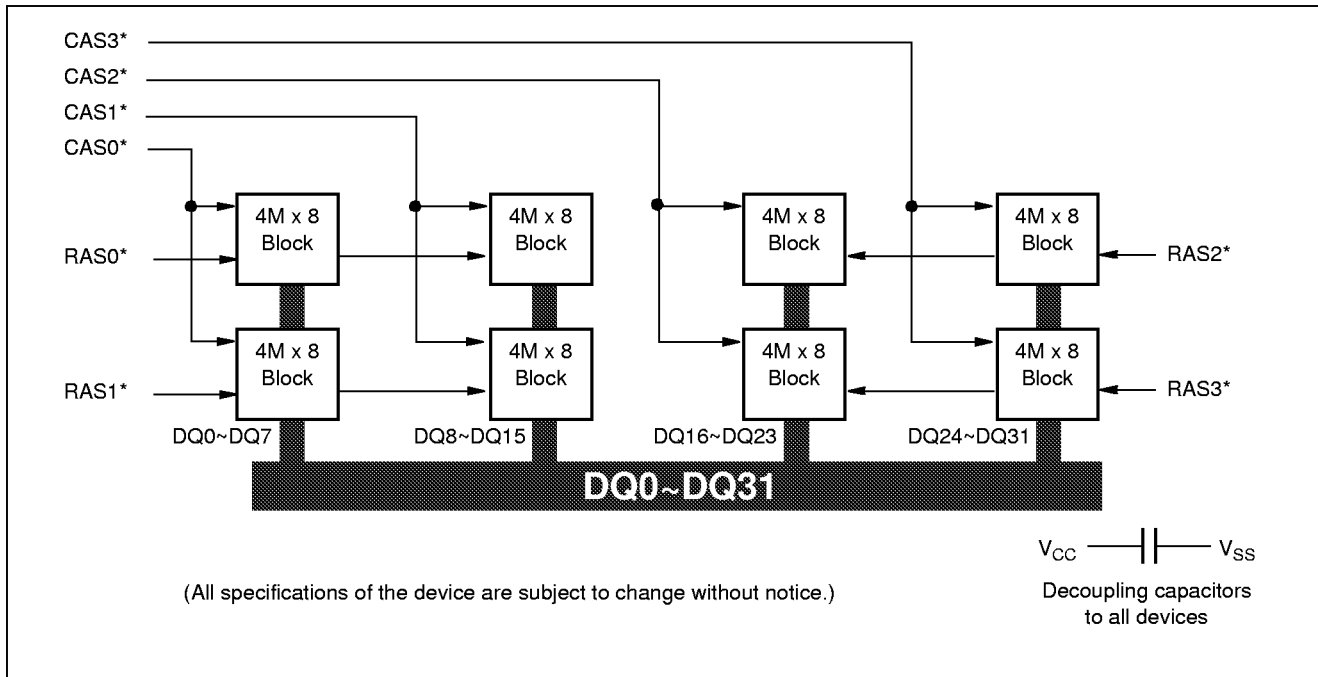
Item	Symbol	Ratings	Unit
Voltage on any pin relative to V _{SS}	V _T	-1 to +7.0	V
Power Dissipation	P _T	8	W
Operating Temperature	T _{opr}	0 to +70	°C
Storage Temperature	T _{stg}	-55 to +125	°C
Short Circuit Output Current	I _{os}	-50 to +50	mA

RECOMMENDED DC OPERATING CONDITIONS

(T_A = 0 to +70 °C)

Symbol	Parameter	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	4.5	5.0	5.5	V
V _{SS}	Ground	0	0	0	V
V _{IH}	Input High voltage	2.4	-	V _{CC} +1	V
V _{IL}	Input Low voltage	-1	-	0.8	V

Functional Diagram



- Notes:
1. A0 ~ A10/A11 to all devices (A11 is NC for 2K refresh module).
 2. WE* to all devices.
 3. OE* of all devices is grounded.
 4. Each 4Mx8 Block consists of two 4Mx4 devices.

ESA8UN324(2/4)(A)-(60/70)(J/T)(G/S)-S

Pin Name

A0~A10†	Addresses for 2K Refresh Module	WE*	Write Enable
A0~A11	Row Addresses for 4K Refresh Module	PD1~PD4	Presence Detects
A0~A9	Column Addresses for 4K Refresh Module	V _{CC}	Power Supply
DQ0~DQ31	Data Inputs/Outputs	V _{SS}	Ground
CAS0*~CAS3*	Column Address Strokes	NC	No Connection
RAS0~RAS3	Row Address Strokes		

Presence Detect Pins

Pin	-60	-70
PD1	NC	NC
PD2	V _{SS}	V _{SS}
PD3	NC	V _{SS}
PD4	NC	NC

Pin No.	Pin Designation	Pin No.	Pin Designation	Pin No.	Pin Designation	Pin No.	Pin Designation
1	V _{SS}	19	A10	37	NC	55	DQ11
2	DQ0	20	DQ4	38	NC	56	DQ27
3	DQ16	21	DQ20	39	V _{SS}	57	DQ12
4	DQ1	22	DQ5	40	CAS0*	58	DQ28
5	DQ17	23	DQ21	41	CAS2*	59	V _{CC}
6	DQ2	24	DQ6	42	CAS3*	60	DQ29
7	DQ18	25	DQ22	43	CAS1*	61	DQ13
8	DQ3	26	DQ7	44	RAS0*	62	DQ30
9	DQ19	27	DQ23	45	RAS1*	63	DQ14
10	V _{CC}	28	A7	46	NC	64	DQ31
11	NC	29	A11†	47	WE*	65	DQ15
12	A0	30	V _{CC}	48	NC	66	NC
13	A1	31	A8	49	DQ8	67	PD1
14	A2	32	A9	50	DQ24	68	PD2
15	A3	33	RAS3*	51	DQ9	69	PD3
16	A4	34	RAS2*	52	DQ25	70	PD4
17	A5	35	NC	53	DQ10	71	NC
18	A6	36	NC	54	DQ26	72	V _{SS}

†: A11 is NC for 2K refresh module.

DC CHARACTERISTICS

 ($V_{CC} = 5.0V \pm 10\%$, $V_{SS} = 0V$, $T_A = 0$ to $+70$ °C)

Parameter	Symbol	Test Condition	Refresh	60		70		Unit	Note
				Min.	Max.	Min.	Max.		
Operating Current	I_{CC1}	RAS*, CAS* cycling; $t_{RC} = \text{min.}$	2K	-	856	-	736	mA	1, 2
			4K	-	616	-	536		
Standby current	I_{CC2}	TTL Interface RAS*, CAS* = V_{IH} $D_{out} = \text{High-Z}$	-	32	-	32	mA		
		CMOS Interface RAS*, CAS* $\geq V_{CC} - 0.2V$ $D_{out} = \text{High-Z}$	-	16	-	16			
RAS* -only Refresh Current	I_{CC3}	CAS* = V_{IH} ; RAS*, Address cycling @ $t_{RC} = \text{min}$	2K	-	856	-	720	mA	2
			4K	-	616	-	536		
CAS*-before-RAS* Refresh Current	I_{CC4}	RAS*, CAS* cycling @ $t_{RC} = \text{min.}$	2K	-	856	-	736	mA	
			4K	-	616	-	536		
Fast Page Mode Current	I_{CC5}	RAS* = V_{IL} ; CAS*, Address cycling @ $t_{PC} = \text{min}$	2K	-	856	-	736	mA	1, 3
			4K	-	616	-	536		
Input Leakage Current	I_{LI}	$0V \leq V_{in} \leq V_{CC} + 0.5V$	-160	160	-160	160	μA		
Output Leakage Current	I_{LO}	$0V \leq V_{out} \leq V_{CC}$ $D_{out} = \text{Disable}$	-20	20	-20	20	μA		
Output High Voltage	V_{OH}	High $I_{out} = -5$ mA	2.4	-	2.4	-	V		
Output Low Voltage	V_{OL}	Low $I_{out} = 4.5$ mA	-	0.4	-	0.4	V		

- Notes:
1. Values depend on load condition when the device is selected. Maximum Values are specified at the output open condition.
 2. Address can be changed once or less while RAS* = V_{IL} .
 3. Address can be changed once or less while CAS* = V_{IH} .

CAPACITANCE

 ($T_A = +25$ °C, $V_{CC} = 5.0V \pm 10\% = 10V$)

Parameter	Symbol	Max.	Unit	Note
Input Capacitance (Address)	C_{I1}	85	pF	1
Input Capacitance (RAS0*~RAS3*)	C_{I2}	25	pF	1
Input Capacitance (CAS0*~CAS3*)	C_{I3}	25	pF	1
Input Capacitance (WE*)	C_{I4}	85	pF	1
Input/Output Capacitance (DQ0~DQ31)	$C_{I/O}$	12	pF	1, 2

- Notes:
1. Capacitance is measured with Boonton Meter or effective capacitance method.
 2. CAS* = V_{IH} to disable D_{out} .

ESA8UN324(2/4)(A)-(60/70)(J/T)(G/S)-S

AC CHARACTERISTICS

(TA = 0 to +70°C, V_{CC} = 5.0V±10%V, V_{SS} = 0V)

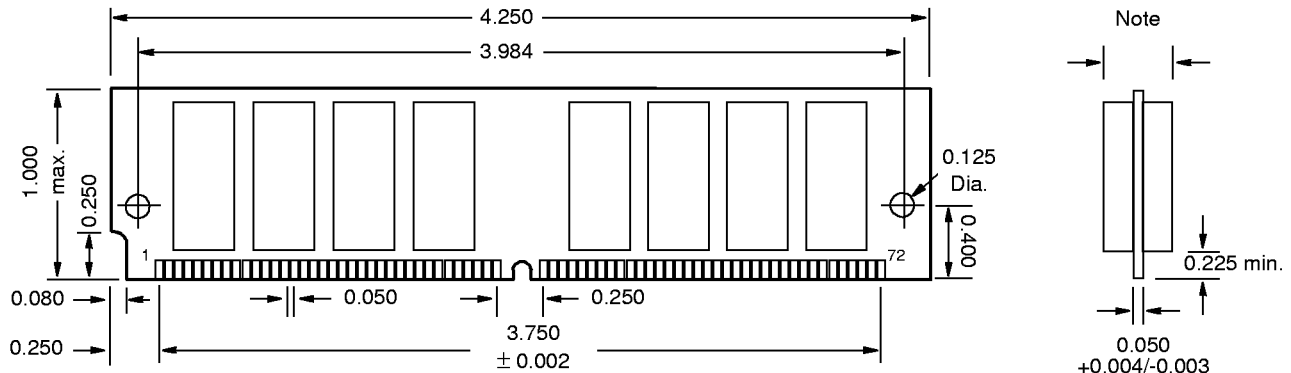
Parameter	Symbol	60		70		Unit	Notes	
		Min	Max	Min	Max			
Random read/write cycle time	t _{RC}	110	-	130	-	ns		
Access time from RAS*	t _{RAC}	-	60	-	70	ns	3, 4	
Access time from CAS*	t _{CAC}	-	15	-	20	ns	3, 4, 5	
Access time from column address	t _{AA}	-	30	-	35	ns	3, 10	
Output buffer turn-off time	t _{OFF}	0	15	0	17	ns	6	
Transition time (rise and fall)	t _T	3	50	3	50	ns	2	
RAS* precharge time	t _{RP}	40	-	50	-	ns		
RAS* pulse width	t _{RAS}	60	10000	70	10000	ns		
RAS* hold time	t _{RSH}	15	-	20	-	ns		
CAS* hold time	t _{CSH}	60	-	70	-	ns		
CAS* pulse width	t _{CAS}	15	10000	20	10000	ns		
RAS* to CAS* delay time	t _{RCD}	20	45	20	50	ns	4	
RAS* to column address delay time	t _{RAD}	15	30	15	35	ns	10	
CAS* to RAS* precharge time	t _{CRP}	5	-	5	-	ns		
Row address set-up time	t _{ASR}	0	-	0	-	ns		
Row address hold time	t _{RAH}	10	-	10	-	ns		
Column address set-up time	t _{ASC}	0	-	0	-	ns		
Column address hold time	t _{CAH}	12	-	15	-	ns		
Column address to RAS* lead time	t _{RAL}	30	-	35	-	ns		
Read command set-up time	t _{RCS}	5	-	5	-	ns		
Read command hold time to CAS*	t _{RCH}	0	-	0	-	ns	8	
Read command hold time to RAS*	t _{RRH}	0	-	0	-	ns		
Write command hold time	t _{WCH}	12	-	15	-	ns		
Write command pulse width	t _{WP}	10	-	15	-	ns		
Write command to RAS* lead time	t _{RWL}	15	-	20	-	ns		
Write command to CAS* lead time	t _{CWL}	15	-	20	-	ns		
Data-in set-up time	t _{DS}	0	-	0	-	ns	9	
Data-in hold time	t _{DH}	12	-	15	-	ns	9	
Refresh period	(2048 cycles)	t _{REF}	-	32	-	32	ms	
	(4096 cycles)		-	64	-	64	ms	
Write command set-up time	t _{WCS}	0	-	0	-	ns	7	
CAS* set-up time (CBR refresh)	t _{CSR}	10	-	10	-	ns	1	
CAS* hold time (CBR refresh)	t _{CHR}	10	-	15	-	ns	1	
RAS* precharge to CAS* hold time	t _{RPC}	5	-	5	-	ns		
Access time from CAS* precharge	t _{CPA}	-	35	-	40	ns	3, 11	
Hyper Page mode cycle time	t _{HPC}	25	-	30	-	ns		
CAS* precharge time (Hyper Page)	t _{CP}	8	-	10	-	ns		
RAS* pulse width (Hyper Page)	t _{RASP}	—	200000	—	200000	ns	12	

ESA8UN324(2/4)(A)-(60/70)(J/T)(G/S)-S

- Notes:
1. An initial pulse of at least 200 μ s is required after power-up followed by a minimum of eight RAS* cycles before device operation is achieved.
 2. V_{IH} (min.) and V_{IL} (max.) are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} (min.) and V_{IL} (max.) and are assumed to be 5 ns for all inputs.
 3. Measure with a load equivalent of 2 TTL loads and 100pF.
 4. Operation within the t_{RCD} (max.) limit ensures that t_{RAC} (max.) limit can be met; t_{RCD} (max.) is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD} (max.) limit, then access time is controlled exclusively by t_{CAC} .
 5. Assumes that $t_{RCD} \geq t_{RCD}$ (max.).
 6. This parameter defines the time at which the output achieves open circuit condition and is not referenced to V_{OH} or V_{OL} .
 7. t_{WCS} is a non restrictive operating parameter. It is included in the data sheet as an electrical characteristic only. If $t_{WCS} \geq t_{WCS}$ (min.) the cycle is an early write cycle and the data-out pin will remain at high impedance for the duration of the cycle.
 8. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
 9. These parameters are referenced to the CAS* leading edge in early write cycles.
 10. Operation within the t_{RAD} (max.) limit ensures that t_{RAC} (max.) can be met. t_{RAD} (max.) is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD} (max.) limit, then access time is controlled by t_{AA} .
 11. Access time is determined by the longer of t_{AA} , t_{CAC} , or t_{ACP} .
 12. t_{RASC} defines RAS* pulse width in fast page mode cycles.

Physical Dimensions

72-pin SIMM



(All dimensions are in inches with ± 0.005 " tolerance unless otherwise specified. Do not scale drawing)

- Notes: Thickness = 0.350 for SOJ DRAM
= 0.150 for TSOP DRAM

ESA8UN3242A - 60JS - S

Ordering Information

E S A 8 U N 32 42 A _ - 60 J S - _ S
(1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13) (14) (15)

(1) **Memory Type**

F : Fast Page Mode (FPM)
E : Extended Data Out (EDO)

(2) **Module Shape**

S : SIMM
D : DIMM
O : Small Outline DIMM

(3) **Module Pin Count**

A : 72-pin
B : 144-pin
C : 168-pin
D : 200-pin

(4) **Word Depth**

1 : 1M
2 : 2M
4 : 4M, etc.

(5) **Buffer Type**

B : Buffered
U : Unbuffered
R : Registered

(6) **Operating Voltage**

N : 5V
V : 3,3V

(7) **Data Width**

(ex. 8=x8, 32=x32, 72=x72 etc.)

(8) **Device Configuration / Refresh**

41 : 1Mx4, 1K Refresh Cycle
42 : 4Mx4, 2K Refresh Cycle
44 : 4Mx4, 4K Refresh Cycle
82 : 2Mx8, 2K Refresh Cycle
14 : 1Mx16, 4K Refresh Cycle
11 : 1Mx16, 1K Refresh Cycle

(9) **Module Revision *1**

Blank : Rev. 0
A : Rev. 1
B : Rev. 2 (etc.)

*1 When DRAM device or PCB is revised, the revision is changed

(10) **Power consumption**

Blank : Standard
L : Low Power

(11) **Speed**

50 : 50ns
60 : 60ns
70 : 70ns

(12) **Package of Component**

J : SOJ
T : TSOP

(13) **Module Lead Finish**

S : Solder Plate
G : Gold Plate

(14) **Private Brand Name *2**

Blank : Common Products
G : FMG Brand

*2 This column is applicable to custom modules, NOT applicable to JEDEC standard commodity products

(15) **Assembly & Test Site**

S : Smart Modular Technologies